Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	55	(carrier ((circuit printed wiring) near1 board)) same (chip die (semiconductor near (device element))) same (flipchip (flip near chip)) same (heat near (spreader spread plate dissipating sink)) same (encapsulant sealing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 16:39
L2	1	1 same (standoff (stand adj off) spacer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 16:38
L3	4010	257/706,707,717,720,796.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 16:37
L4	2078	438/122,123.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 16:38
L5	5865	3 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 16:38
L6	0	5 same (standoff (stand adj off) spacer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 16:39
L7	481	5 and (standoff (stand adj off) spacer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 16:39
L8	126	7 and (carrier ((circuit printed wiring) near1 board)) and (chip die (semiconductor near (device element))) and (flipchip (solder adj (bump ball)) (flip near chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 16:40

L9	123	8 not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/01 16:40